

SJ105215  
( 'ON 0NIMVHO) 台 票 圖 號

DESIGNATION

MM60-52B1-B\*  
 SERIES PREFIX  
 No. OF CONTACTS  
 SOCKET TYPE  
 KEYING TYPE  
 CONTACT FINISH  
 1: Au(0.14μm Min.) OVER NI  
 2: Au(0.34μm Min.) OVER NI  
 MODIFY CODE  
 B: 3.9mm HIGH WITH BOSS

| 版数 REV. | 年月日 DATE    | DCN NO. | 変更内容 DESCRIPTION    | 製図 DR. | 担当 CHK.  | 査閲 APPD. | 承認 APPD.   |
|---------|-------------|---------|---------------------|--------|----------|----------|------------|
| 2       | 23.Jan.2006 | 059045  | CHANGED BOSS LENGTH |        | Y.YAHIRO |          | K.HISATOMI |

NOTE 1. PRODUCTION LOT No. AS INDICATED.

( Ex. ) T501

LOT NUMBER OF CURRENT MONTH  
 MONTH ( 1 TO 9 FOR JAN. TO SEPT. RESPECTIVELY,  
 OCT.:0, NOV.:X, DEC.:Y )  
 YEAR ( LAST DIGIT ONLY )  
 MANUFACTURE CODE

NOTE 2. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION.

NOTE 3. BEVEL MUST BE FREE OF CUTTING BURRS.

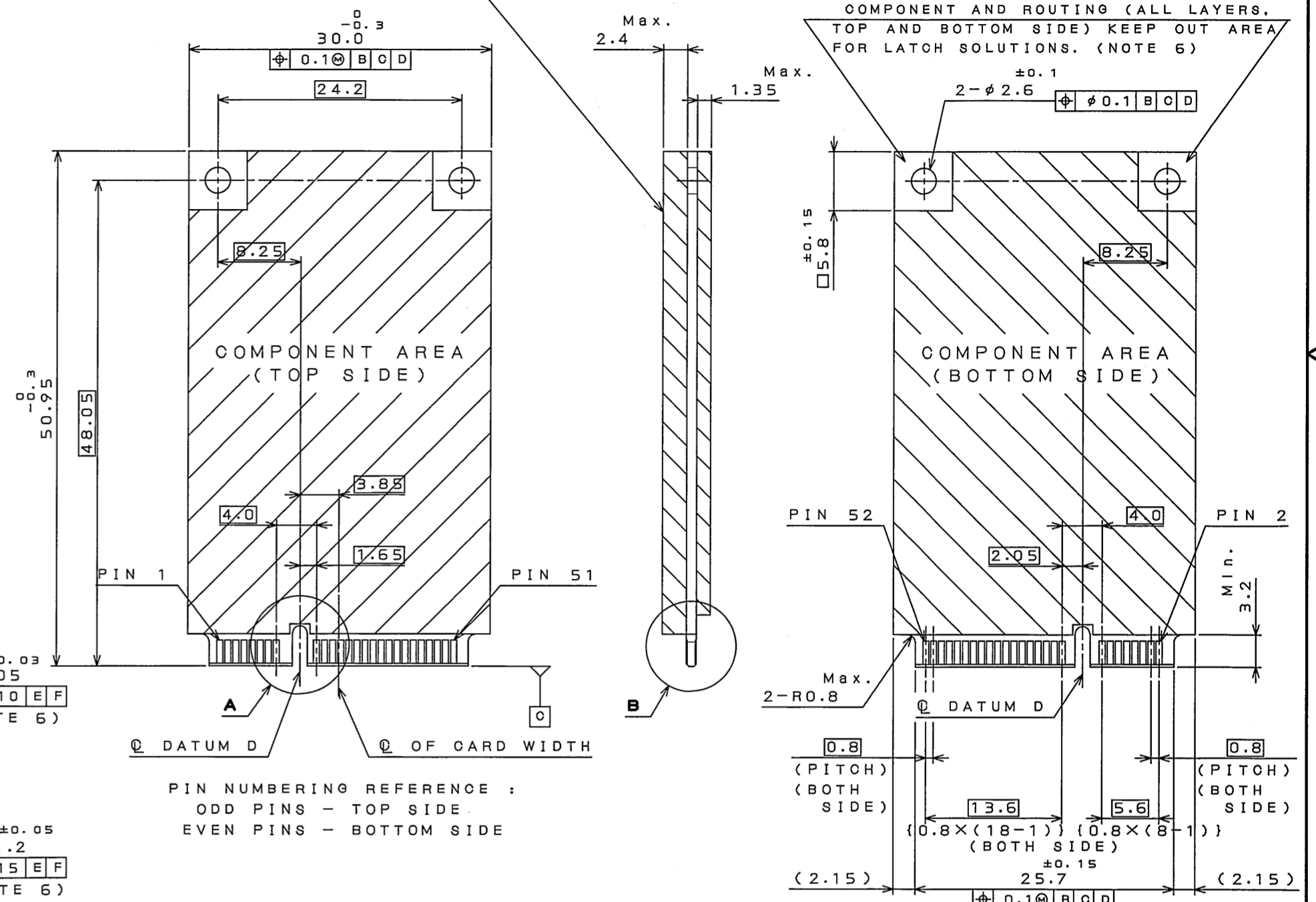
NOTE 4. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE φ1.6 AND φ1.1 HOLES.  
 THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM F.

NOTE 5. LOCATION OF INSERTED CARD EDGE IS ALIGNED WITH Q OF HOLES.

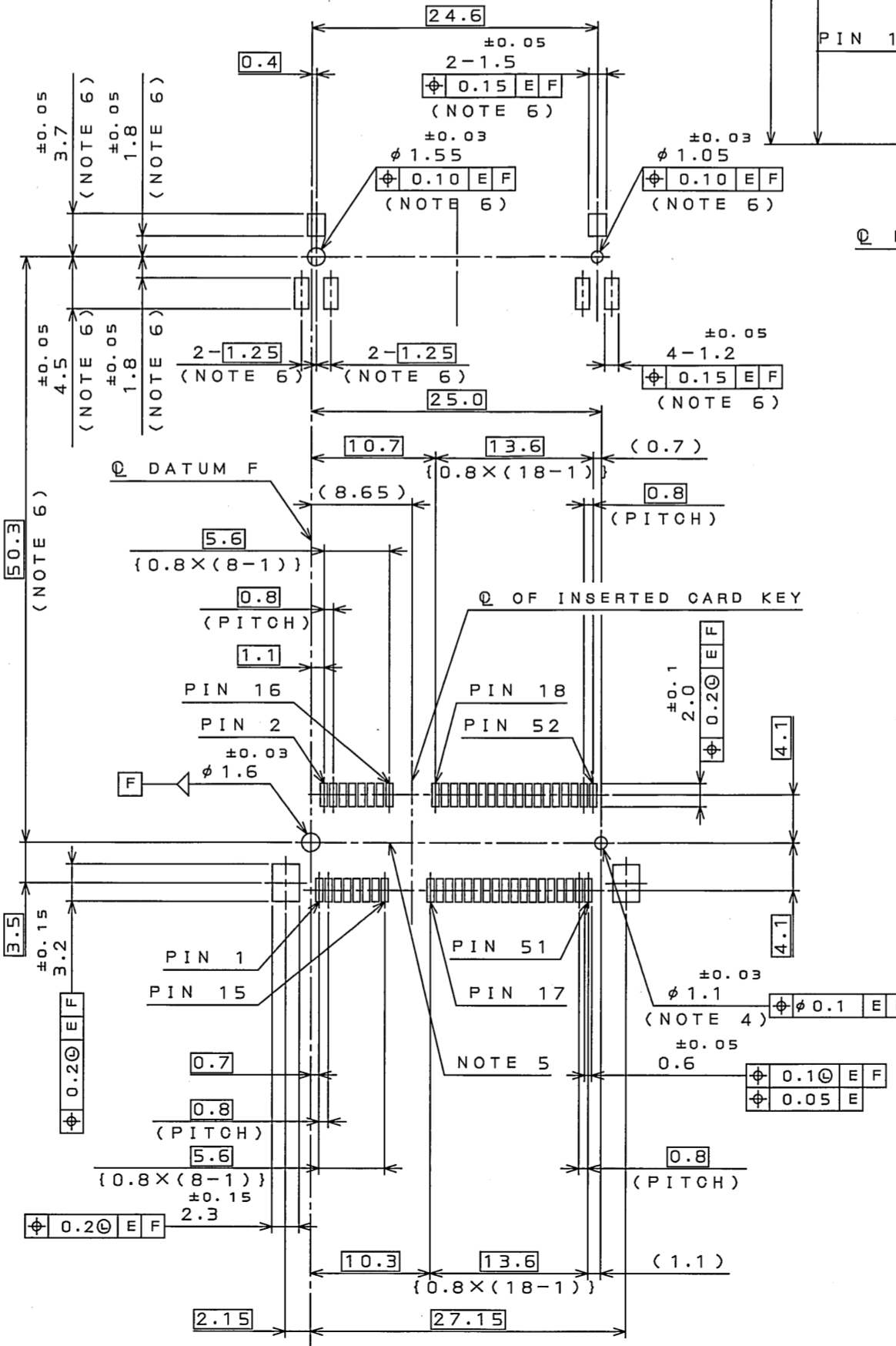
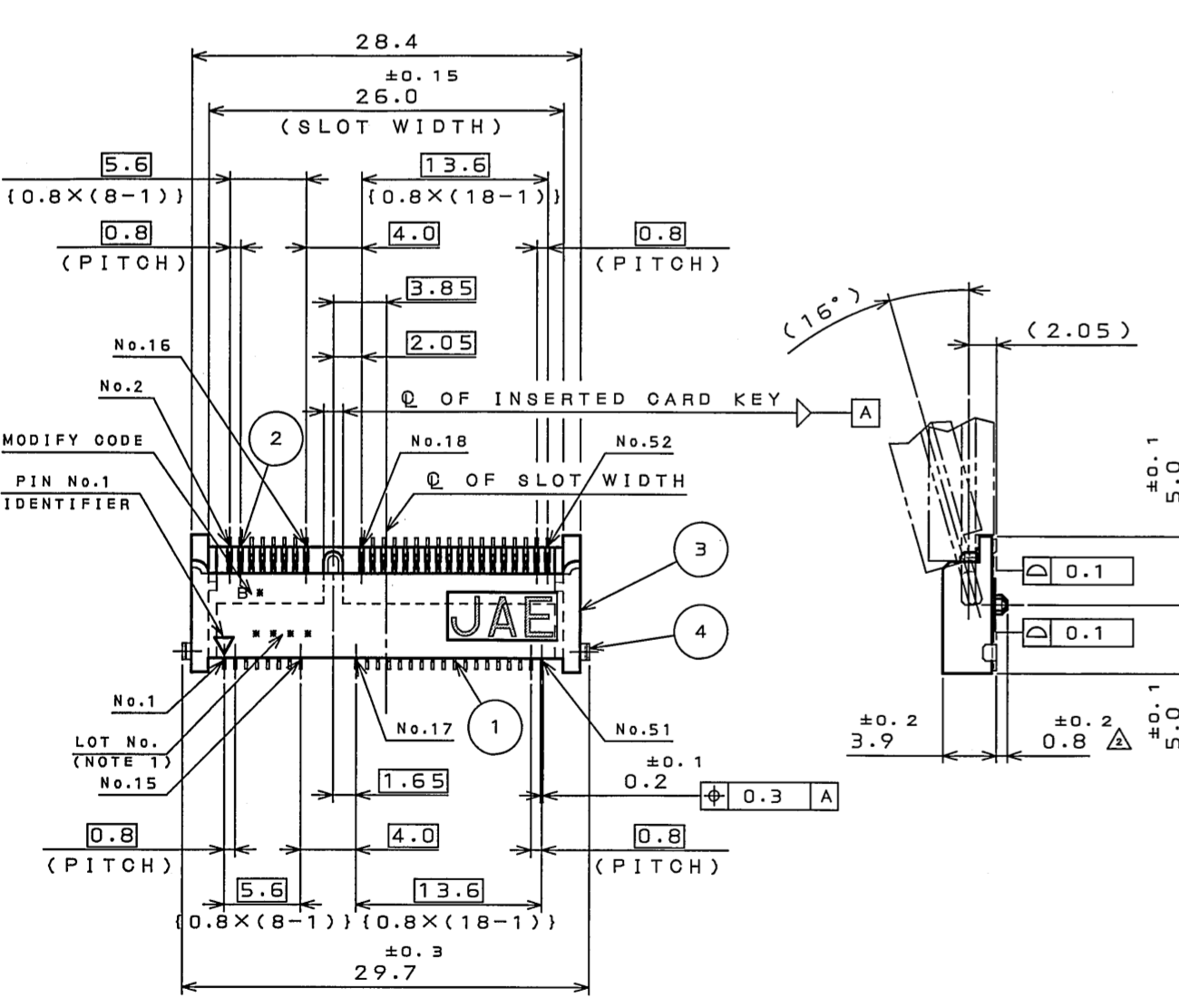
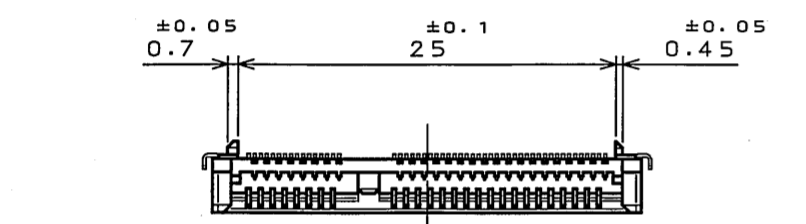
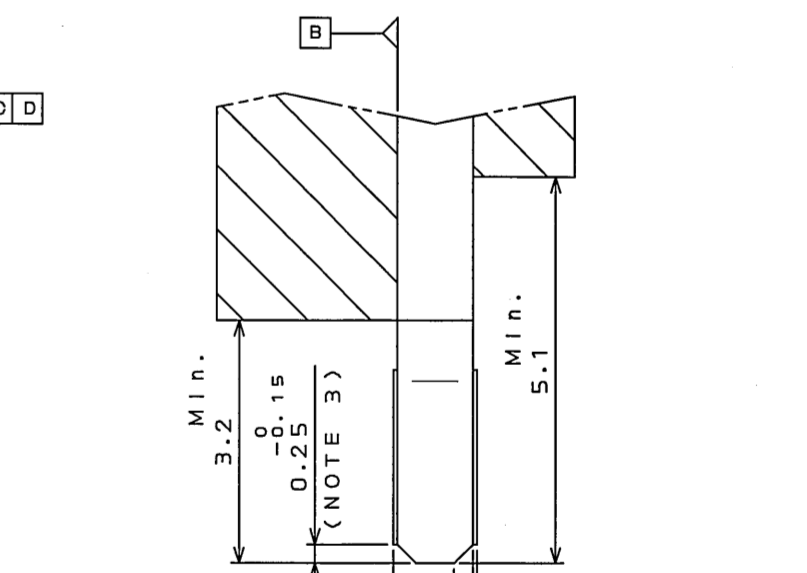
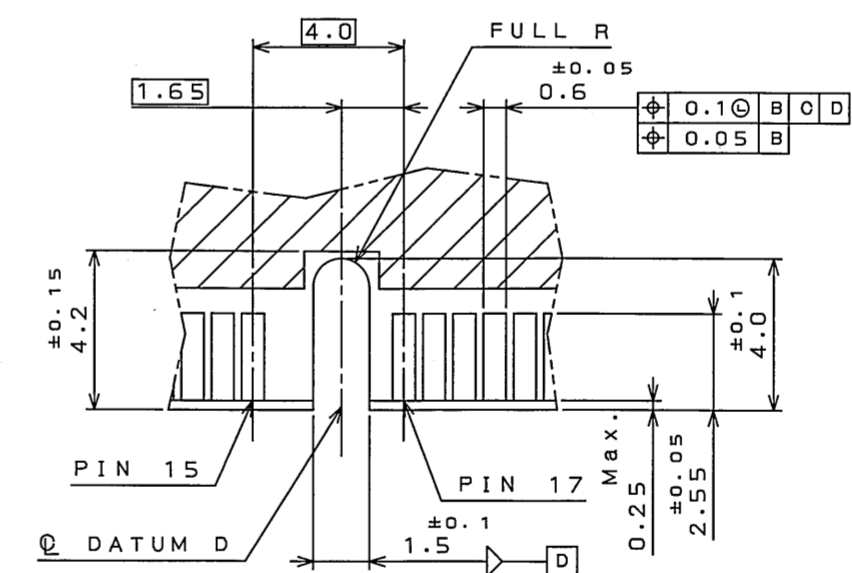
NOTE 6. ONLY WHEN THE LATCH SHOWN IN SJ105217(MM60-EZH039-B5) IS USED, THESE DIMENSIONS ARE APPLIED.

HATCHED AREAS ILLUSTRATE MAXIMUM AVAILABLE COMPONENT VOLUME.  
 APPLICABLE DIMM(REF.)

COMPONENT AND ROUTING ( ALL LAYERS, TOP AND BOTTOM SIDE ) KEEP OUT AREA FOR LATCH SOLUTIONS. ( NOTE 6 )



PIN NUMBERING REFERENCE :  
 ODD PINS - TOP SIDE  
 EVEN PINS - BOTTOM SIDE



| 符号 NO. | 名 称 DESCRIPTION     | 個 数 QTY. | 材 料 MATERIAL  | 材 質 FINISH  | 備 考 REMARKS  |
|--------|---------------------|----------|---------------|-------------|--|
| 4      | HOLD DOWN           | 2        | COPPER ALLOY  | TIN PLATING |  |
| 3      | INSULATOR           | 1        | THERMOPLASTIC |             | UL94 V-0   |
| 2      | BOTTOM SIDE CONTACT | 26       | COPPER ALLOY  |             | CONTACT AREA : Au OVER NI<br>SOLDERING AREA : GOLD FLASH OVER NI |
| 1      | TOP SIDE CONTACT    | 26       | COPPER ALLOY  |             | CONTACT AREA : Au OVER NI<br>SOLDERING AREA : GOLD FLASH OVER NI |

| 仕 様 書 ( SPECIFICATION ) | 第 1 版 ( ORIGINAL DATE ) | 尺 寸 ( SCALE ) | シ リ ー ズ ( SERIES ) | 製 図 者 ( DRAWING NO. ) |
|-------------------------|-------------------------|---------------|--------------------|-----------------------|
| JACS-10313              | 5.Dec.2005              | 2:1           | MM60               | 日本航空電子工業株式会社          |

| 最 大 差 ( GENERAL TOLERANCE ) | 名 称 ( TITLE ) |
|-----------------------------|---------------|
| . ±0.8 ° ±                  | MM60-52B*-B*  |
| .X ±0.4 ° ±                 |               |
| .XX ±0.1 ° ±                |               |
| .XXX ±                      |               |

| 製 図 者 ( DR. ) | 担 当 ( CHK. ) | 査 閲 ( APPD. ) | 承 認 ( APPD. ) |
|---------------|--------------|---------------|---------------|
|               | Y.YAHIRO     |               | K.HISATOMI    |

| 重 量 ( MASS ) |
|--------------|
|              |

DATUM E IS THE TOP OF SURFACE OF PCB.  
 APPLICABLE P.C.B. DIMENSION(REF.)  
 適合基板寸法(参考)

DOF-0-313F(05.08)

